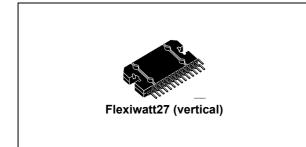


TDA75612LV

4 x 45 W power amplifier with full I²C diagnostics, SSR and low voltage operation

Datasheet - production data



Features

- Multipower BCD technology
- MOSFET output power stage
- DMOS power output
- High output power capability 4x25 W/4 Ω @ 14.4 V, 1 kHz, 10% THD, 4 x 45 W max power
- 2 Ω driving capability (64 W max power)
- Full I²C bus driving:
 - Standby
 - Independent front/rear soft play/mute
 - Selectable gain 30 dB /16 dB (for low noise line output function)
 - I²C bus digital diagnostics (including DC and AC load detection)
- Flexible fault detection through integrated diagnostic
- DC offset detection
- Four independent short circuit protection
- Clipping detector pin with selectable threshold (2 %/10 %)

- Standby/mute pin
- Linear thermal shutdown with multiple thermal warning
- ESD protection
- Very robust against misconnections
- Improved SVR suppression during battery transients
- Capable to operate down to 6 V (e.g. "Start-stop")
- Enableable SSR (speaker safety routine)

Description

The TDA75612LV is a new quad bridge car radio amplifier, designed in BCD technology, in order to include a wide range of innovative features in a very compact and flexible device.

The TDA75612LV is equipped with the most complete diagnostics array that communicates the status of each speaker through the I^2C bus.

TDA75612LV has been designed to be very robust against several kinds of misconnections.

The TDA75612LV is equipped with the SSR (speaker safety routine), a procedure able to check the offset at the speakers and automatically shut down the power amplifier in case of dangerous DC voltage.

It is moreover compliant to the most recent OEM specifications for low voltage operation (so called 'start-stop' battery profile during engine stop), helping car manufacturers to reduce the overall emissions and thus contributing to environment protection.

Table 1. Device summary

Order code	Package	Packing
TDA75612LV-48X	Flexiwatt27 (vertical)	Tube

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1 Block diagram and application circuits

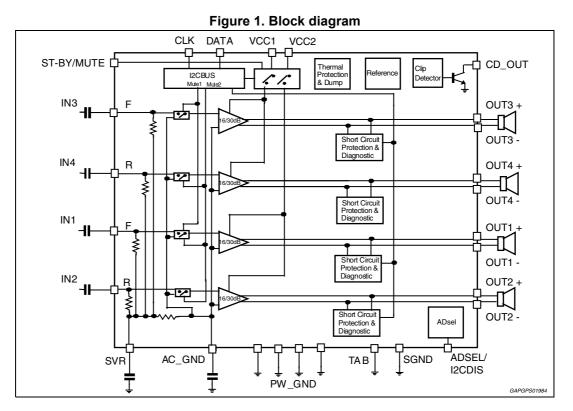
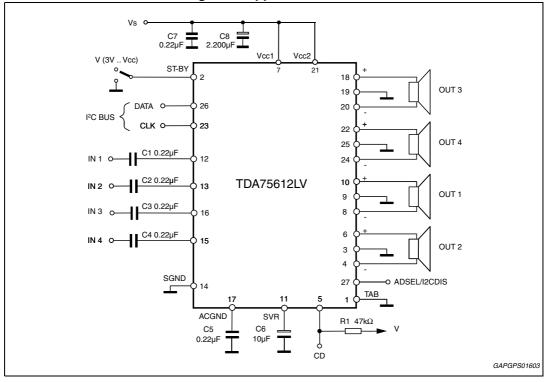


Figure 2. Application circuit





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2 Pins description

For channel name reference: CH1 = LF, CH2 = LR, CH3 = RF and CH4 = RR.

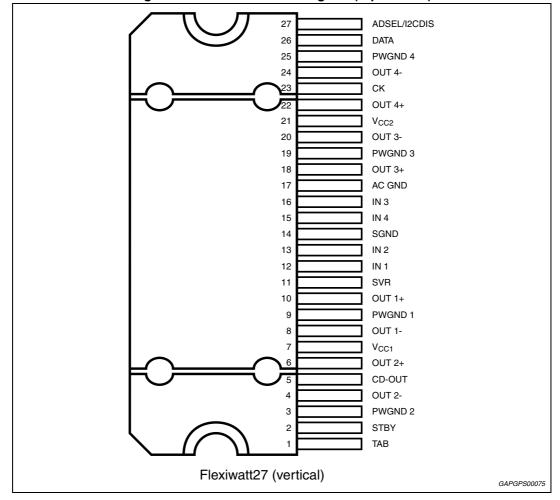






Table 2. Pins list description				
Pin #	Pin name	Function		
1	TAB	-		
2	STBY	Standby pin		
3	PWGND2	Channel 2 output power ground		
4	OUT2-	Channel 2, - output		
5	CD	Clip detector output pin		
6	OUT2+	Channel 2, + output		
7	VCC1	Supply voltage pin1		
8	OUT1-	Channel 1, - output		
9	PWGND1	Channel 1 output power ground		
10	OUT1+	Channel 1, + output		
11	SVR	SVR pin		
12	IN1	Input pin, channel 1		
13	IN2	Input pin, channel 2		
14	SGND	Signal ground pin		
15	IN4	Input pin, channel 4		
16	IN3	Input pin, channel 3		
17	AC GND	AC ground		
18	OUT3+	Channel 3, + output		
19	PWGND3	Channel 3 output power ground		
20	OUT3-	Channel 3, - output		
21	VCC2	Supply voltage pin2		
22	OUT4+	Channel 4, + output		
23	СК	I ² C bus clock		
24	OUT4-	Channel 4, - output		
25	PWGND4	Channel 4 output power ground		
26	DATA	I ² C bus data pin/gain selector		
27	ADSEL/I2CDIS	Address selector pin/ I ² C bus disable (legacy select)		

Table 2. Pins list description



3 Electrical specifications

3.1 Absolute maximum ratings

	93	
Parameter	Value	Unit
Operating supply voltage ⁽¹⁾	18	V
DC supply voltage	28	V
Peak supply voltage (for t _{max} = 50 ms)	50	V
Ground pins voltage	-0.3 to 0.3	V
CK and DATA pin voltage	-0.3 to 6	V
Clip detector voltage	-0.3 to 5.5	V
STBY pin voltage	-0.3 to Vop	V
Output peak current (not repetitive t _{max} = 100ms)	8	^
Output peak current (repetitive f > 10 kHz)	6	- A
Power dissipation T _{case} = 70°C	85	W
Storage and junction temperature ⁽²⁾	-55 to 150	°C
Operative temperature range	-40 to +105	°C
	ParameterOperating supply voltageDC supply voltagePeak supply voltage (for $t_{max} = 50 \text{ ms}$)Ground pins voltageCK and DATA pin voltageClip detector voltageSTBY pin voltageOutput peak current (not repetitive $t_{max} = 100 \text{ ms}$)Output peak current (repetitive $f > 10 \text{ kHz}$)Power dissipation $T_{case} = 70^{\circ}\text{C}$ Storage and junction temperature ⁽²⁾	Operating supply voltage18DC supply voltage28Peak supply voltage (for $t_{max} = 50 \text{ ms}$)50Ground pins voltage-0.3 to 0.3CK and DATA pin voltage-0.3 to 6Clip detector voltage-0.3 to 5.5STBY pin voltage-0.3 to VopOutput peak current (not repetitive $t_{max} = 100 \text{ms}$)8Output peak current (repetitive $f > 10 \text{ kHz}$)6Power dissipation $T_{case} = 70^{\circ}\text{C}$ 85Storage and junction temperature ⁽²⁾ -55 to 150

Table 3. Absolute maximum ratings

1. For R_L = 2 Ω the output current limit might be reached for V_{OP} > 16 V; thus triggering self-protection.

2. A suitable dissipation system should be used to keep T_{j} inside the specified limits.

3.2 Thermal data

Table 4. Thermal data

Symbol	Parameter	Value	Unit
R _{th j-case}	Thermal resistance junction-to-case Max.	1	°C/W



3.3 Electrical characteristics

Refer to the test circuit, V_S = 14.4 V; R_L = 4 Ω ; f = 1 kHz; G_V = 30 dB; T_{amb} = 25 °C; unless otherwise specified.

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
General c	haracteristics					
		R _L = 4 Ω	6	-	18	
V _S	Supply voltage range	R _L = 2 Ω	6	-	16 ⁽¹⁾	V
I _d	Total quiescent drain current	-	-	165	250	mA
R _{IN}	Input impedance	-	45	60	70	kΩ
		IB1(D7) = 1	7	-	8	
V _{AM}	Min. supply mute threshold	IB1(D7) = 0 (default) ⁽²⁾	5	-	6	V
V _{OS}	Offset voltage	Mute & play	-100	-	100	mV
V _{dth}	Dump threshold	-	18.5	-	20.5	V
I _{SB}	Standby current	V _{standby} = 0	-	1	5	μA
SVR	Supply voltage rejection	f = 100 Hz to 10 kHz; V _r = 1 Vpk; R _g = 600 Ω	60	70	-	dB
T _{ON}	Turn on timing (Mute play transition)	D2/D1 (IB1) 0 to 1	-	25	50	ms
T _{OFF}	Turn off timing (Play mute transition)	D2/D1 (IB1) 1 to 0	-	25	50	ms
TH _{WARN1}	Average junction temperature for TH warning 1	DB1 (D7) = 1	-	155	-	
TH _{WARN2}	Average junction temperature for TH warning 2	DB4 (D7) = 1	-	140	-	°C
TH _{WARN3}	Average junction temperature for TH warning 3	DB4 (D6) = 1	-	125	-	
Audio per	formances					•
		Max. power ⁽³⁾ V _s = 15.2 V, R _L = 4 Ω	-	45	-	W
		THD = 10 %, R _L = 4 Ω	23	25		W
		THD = 1 %, R _L = 4 Ω	-	22	-	W
PO	Output power	R _L = 2 Ω; THD 10 %		44		W
		$R_L = 2 \Omega$; THD 1 %	-	33	-	W
		R _L = 2 Ω; Max. power ⁽³⁾ V _s = 14.4 V		64		W
		Max power@ V _s = 6 V, R _L = 4 Ω	-	5	-	W
		P _O = 1 W to 10 W	-	0.015	0.1	%
THD	Total harmonic distortion	P _O = 1-10 W, f = 10 kHz	-	0.15	0.5	%
		G_V = 16 dB; V_O = 0.1 to 5 VRMS	-	0.01	0.05	%
CT	Cross talk	f = 1 kHz to 10 kHz, R_g = 600 Ω	50	65	-	dB
G _{V1}	Voltage gain 1	-	29	30	31	dB

Table 5. Electrical characteristic	S
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Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
ΔG_{V1}	Voltage gain match 1	-	-1	-	1	dB
G _{V2}	Voltage gain 2	-	15	16	17	dB
ΔG_{V2}	Voltage gain match 2	-	-1	-	1	dB
E _{IN1}	Output noise voltage 1	R_g = 600 Ω 20 Hz to 22 kHz	-	65	80	μV
E _{IN2}	Output noise voltage 2	R _g = 600 Ω; GV = 16d B 20 Hz to 22 kHz	-	20	30	μV
BW	Power bandwidth	-	100	-	-	KHz
CMRR	Input CMRR	V_{CM} = 1 Vpk-pk; Rg = 0 Ω	-	70	-	dB
		Standby to Mute and Mute to Standby transition T_{amb} = 25 °C, ITU-R 2K, C _{svr} = 10 µF V _s = 14.4 V	-7.5	-	+7.5	mV
ΔV _{OITU}	V _{OITU} ITU Pop filter output voltage	Mute to Play transition T_{amb} = 25 °C, ITU-R 2K, V _s = 14.4 V ⁽⁴⁾	-10	-	+10	mV
		Play to Mute transition T_{amb} = 25 °C, ITU-R 2K, V _s = 14.4 V ⁽⁵⁾	-10	-	+10	mV
Clip detec	ctor					
CD _{LK}	Clip det. high leakage current	CD off / V _{CD} = 6 V	-	0	5	μA
CD _{SAT}	Clip det sat. voltage	CD on; I _{CD} = 1 mA	-	-	300	mV
	Clin dat TI ID Javal	D0 (IB1) = 1	5	10	15	%
CD _{THD}	Clip det THD level	D0 (IB1) = 0	1	2	3	%
Control p	in characteristics					
V _{SBY}	Standby/mute pin for standby	-	0	-	1.2	V
V _{MU}	Standby/mute pin for mute	-	2.9	-	3.5	V
V _{OP}	Standby/mute pin for operating	-	4.5	-	18	V
	Standby/muta nin averant	V _{st-by/mute} = 4.5 V	-	1	5	μA
I _{MU}	Standby/mute pin current	V _{st-by/mute} < 1.2 V	-	0	5	μA
A _{SB}	Standby attenuation	-	90	110	-	dB
A _M	Mute attenuation	-	80	100	-	dB

Table 5. Electrical characteristics (continued)



Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
Turn on d	iagnostics 1 (Power amplifier mo	de)				
Pgnd	Short to GND det. (below this limit, the Output is considered in short circuit to GND)		-	-	1.2	V
Pvs	Short to Vs det. (above this limit, the output is considered in short circuit to Vs)		Vs -1.2	-	-	V
Pnop	Normal operation thresholds. (Within these limits, the output is considered without faults).	Power amplifier in standby	1.8	-	Vs -1.8	V
Lsc	Shorted load det.		-	-	0.5	Ω
Lop	Open load det.		85	-	-	Ω
Lnop	Normal load det.		1.5	-	45	Ω
Turn on d	iagnostics 2 (Line driver mode)					
Pgnd	Short to GND det. (below this limit, the output is considered in short circuit to GND)	Power amplifier in standby	-	-	1.2	V
Pvs	Short to V_s det. (above this limit, the output is considered in short circuit to V_s)	-	Vs -1.2	-	-	V
Pnop	Normal operation thresholds. (Within these limits, the output is considered without faults).	-	1.8	-	Vs -1.8	V
Lsc	Shorted load det.	-	-	-	1.5	Ω
Lop	Open load det.	-	330	-	-	Ω
Lnop	Normal load det.	-	7	-	180	Ω
Permaner	nt diagnostics 2 (Power amplifier	mode or line driver mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in short circuit to GND)		-	-	1.2	V
Pvs	Short to V_s det. (above this limit, the output is considered in short circuit to V_s)	Power amplifier in mute or play, one or more short circuits protection activated	Vs -1.2	-	-	V
Pnop	Normal operation thresholds. (Within these limits, the output is considered without faults).		1.8	-	Vs -1.8	V
	Shorted load det.	Power amplifier mode	-	-	0.5	Ω
L _{SC}		Line driver mode	-	-	1.5	Ω
Vo	Offset detection	Power amplifier in play, AC input signals = 0	±1.5	±2	±2.5	V



Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit	
I _{NLH}	Normal load current detection	V _O < (V _S -5)pk, IB2 (D7) = 0	500	-	-	mA	
I _{OLH}	Open load current detection	$v_0 < (v_s - 3)pk, IBZ (D7) = 0$	-	-	250	mA	
I _{NLL}	Normal load current detection	V _O < (V _S -5)pk, IB2 (D7) = 1	250	-	-	mA	
I _{OLL}	Open load current detection	$v_0 < (v_s - 3)pk, IBZ (D7) = 1$	-	-	125	mA	
I ² C bus in	I ² C bus interface						
S _{CL}	Clock frequency	-	-	-	400	kHz	
V _{IL}	Input low voltage	-	-	-	1.5	V	
V _{IH}	Input high voltage	-	2.3	-	-	V	

Table 5. Electrical characteristics (continued)

1. When V_S > 16 V the output current limit is reached (triggering embedded internal protections).

2. In legacy mode only low threshold option is available.

3. Saturated square wave output.

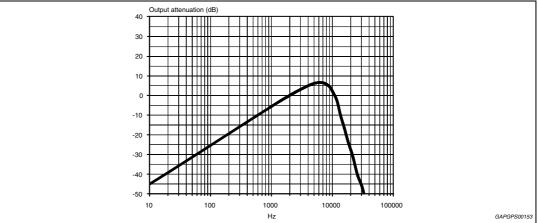
4. Voltage ramp on STBY pin:

from 3.3 V to 4.2 V in t \ge 40 ms. In case of I²C mode command IB1(D1) = 1 (Mute \rightarrow Unmute rear channels) and/or IB1(D2) = 1 (Mute \rightarrow Unmute front channels) must be transmitted before to start the voltage ramp on STBY pin.

5. Voltage ramp on STBY pin:

from 4.05 V to 3.55 V in t \ge 40 ms. In case of I²C mode command IB1(D1) = 0 Unmute \rightarrow Mute rear channels) and/or IB1(D2) = 0 (Unmute \rightarrow Mute front channels) must be NOT transmitted before to start the voltage ramp on STBY pin.







Diagnostics functional description 4

Turn-on diagnostic 4.1

It is recommended to activate this function at the turn-on (standby out) through an I²C bus request. Detectable output faults are:

- Short to GND
- Short to Vs
- Short across the speaker
- Open speaker

To verify if any of the above misconnections are in place, a subsonic (inaudible) current pulse (Figure 5) is internally generated, sent through the speaker(s) and sunk back. The Turn-on diagnostic status is internally stored until a successive diagnostic pulse is requested (after a I²C reading).

If the "standby out" and "diag. enable" commands are both given through a single programming step, the pulse takes place first (during the pulse the power stage stays 'off', showing high impedance at the outputs).

Afterwards, when the Amplifier is biased, the PERMANENT diagnostic takes place. The previous Turn-on state is kept until a short appears at the outputs.

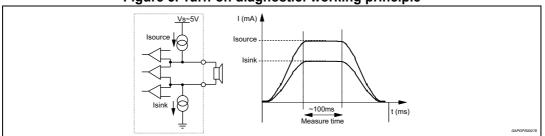


Figure 5. Turn-on diagnostic: working principle

Figure 6 and 7 show SVR and OUTPUT waveforms at the turn-on (standby out) with and without turn-on diagnostic.

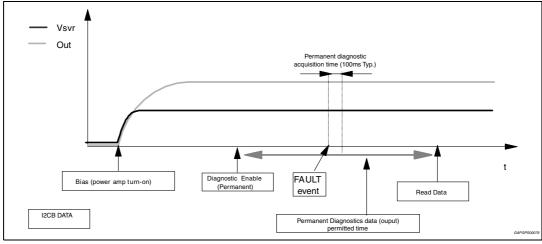


Figure 6. SVR and output behavior (Case 1: without turn-on diagnostic)



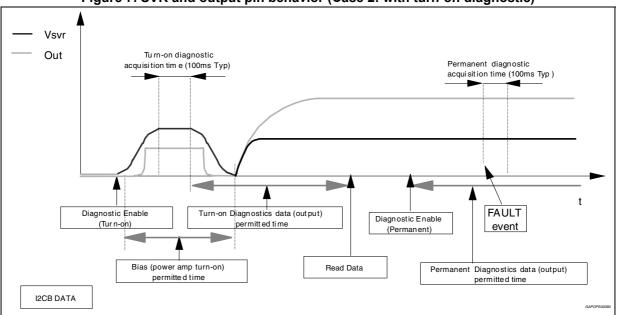
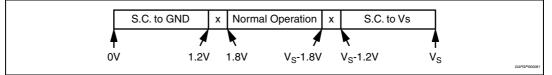


Figure 7. SVR and output pin behavior (Case 2: with turn-on diagnostic)

The information related to the outputs status is read and memorized at the end of the current pulse plateau. The acquisition time is 100 ms (typ.). No audible noise is generated in the process. As for Short to GND / V_s the fault-detection thresholds remain unchanged from 30 dB to 16 dB gain setting. They are as follows:





Concerning Short across the speaker / Open speaker, the threshold varies from 30 dB to 16 dB gain setting, since different loads are expected (either normal speaker's impedance or high impedance). The values in case of 30 dB gain are as follows:





If the Line Driver mode (G_v = 16 dB and Line Driver Mode diagnostic = 1) is selected, the same thresholds will change as follows:

Figure 10. Load detection threshold - low gain setting

				-	
S.C. across Load	х	Normal Operation	x	Open Loa	d
4		h ,		N	
Ω 1.5Ω	2	7Ω 180	Ω	330Ω	infinit



4.2 Permanent diagnostics

Detectable conventional faults are:

- Short to GND
- Short to V_s
- Short across the speaker

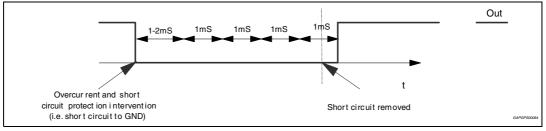
The following additional features is provided:

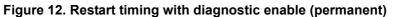
• Output offset detection (see Section 5)

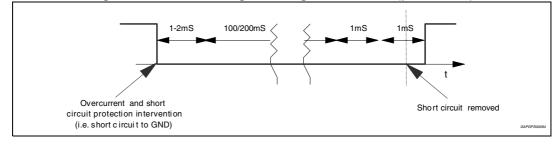
The TDA75612LV has 2 operating statuses:

- RESTART mode. The diagnostic is not enabled. Each audio channel operates independently from each other. If any of the a.m. faults occurs, only the channel(s) interested is shut down. A check of the output status is made every 1 ms (*Figure 11*). Restart takes place when the overload is removed.
- 2. DIAGNOSTIC mode. It is enabled via I²C bus and self activates if an output overload (such to cause the intervention of the short-circuit protection) occurs to the speakers outputs. Once activated, the diagnostics procedure develops as follows (*Figure 12*):
 - To avoid momentary re-circulation spikes from giving erroneous diagnostics, a check of the output status is made after 1ms: if normal situation (no overloads) is detected, the diagnostic is not performed and the channel returns back active.
 - Instead, if an overload is detected during the check after 1 ms, then a diagnostic cycle having a duration of about 100 ms is started.
 - After a diagnostic cycle, the audio channel interested by the fault is switched to RESTART mode. The relevant data are stored inside the device and can be read by the microprocessor. When one cycle has terminated, the next one is activated by an I²C reading. This is to ensure continuous diagnostics throughout the carradio operating time.
 - To check the status of the device a sampling system is needed. The timing is chosen at microprocessor level (over half a second is recommended).

Figure 11. Restart timing without diagnostic enable (permanent) - Each 1 mS time, a sampling of the fault is done







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4.3 AC diagnostic

It is targeted at detecting accidental disconnection of tweeters in 2-way speaker and, more in general, presence of capacitive (AC) coupled loads.

This diagnostic is based on the notion that the overall speaker's impedance (woofer + parallel tweeter) will tend to increase towards high frequencies if the tweeter gets disconnected, because the remaining speaker (woofer) would be out of its operating range (high impedance). The diagnostic decision is made according to peak output current thresholds, and it is enabled by setting (IB2-D2) = 1. Two different detection levels are available:

- High current threshold IB2 (D7) = 0 lout > 500 mApk = normal status lout < 250 mApk = open tweeter
- Low current threshold IB2 (D7) = 1 lout > 250 mApk = normal status lout < 125 mApk = open tweeter

To correctly implement this feature, it is necessary to briefly provide a signal tone (with the amplifier in "play") whose frequency and magnitude are such as to determine an output current higher than 500 mApk with IB2(D7) = 0 (higher than 250 mApk with IB2(D7) = 1) in normal conditions and lower than 250 mApk with IB2(D7) = 0 (lower than 125 mApk with IB2(D7) = 1) should the parallel tweeter be missing.

The test has to last for a minimum number of 3 sine cycles starting from the activation of the AC diagnostic function IB2<D2>) up to the I^2C reading of the results (measuring period). To confirm presence of tweeter, it is necessary to find at least 3 current pulses over the above threadless over all the measuring period, else an "open tweeter" message will be issued.

The frequency / magnitude setting of the test tone depends on the impedance characteristics of each specific speaker being used, with or without the tweeter connected (to be calculated case by case). High-frequency tones (> 10 kHz) or even ultrasonic signals are recommended for their negligible acoustic impact and also to maximize the impedance module's ratio between with tweeter-on and tweeter-off.

Figure 13 and *14* shows the load impedance as a function of the peak output voltage and the relevant diagnostic fields.

It is recomended to keep output voltage always below 8 V (high threshold case) or 4 V (low threshold case) to avoid the circuit to saturate (causing wrong detection cases).

This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.



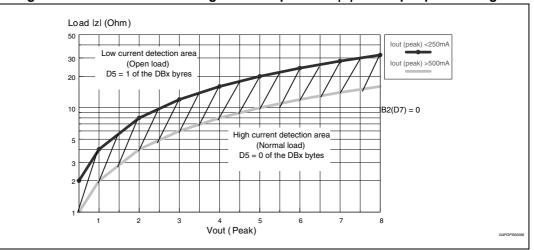
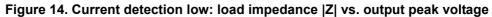
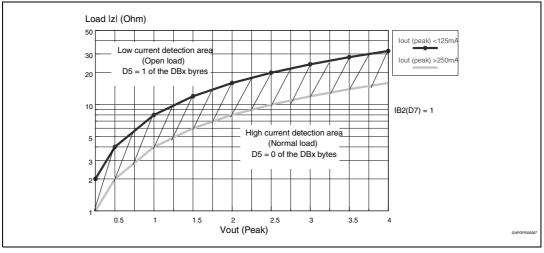


Figure 13. Current detection high: load impedance |Z| vs. output peak voltage







Output DC offset detection 5

The TDA75612LV can detect any DC output offset exceeding ±2 V. This inconvenient might occur as a consequence of initially defective or aged and worn-out input capacitors feeding a DC component to the inputs, so putting the speakers at risk of overheating.

Every time the power amplifier switches on, the SSR automatically mutes the device in case of offset.

In play mode, the offset is signalled out on I²C bus.

5.1 Offset detection and mute at start-up, SSR (Speaker Safety **Routine**)

TDA75612LV embeds a speaker safety routine in order to protect the speakers in case of big output offset. This protection mechanism can automatically mute the device within 40 ms when it detects an offset bigger than 2 V at the output. No external circuit is required for this feature.

The SSR requires the MCU to turn on the audio power amplifier in a proper sequence. The MCU should at first turn on the device in MUTE condition and, after a suitable time to completely power on the device, which is about 1s, send a PLAY command to it and make sure there is no signal applied to any of the inputs for at least 100 ms.

The SSR can be enabled acting on IB2-D0 bit.

See Figure 15. The power amplifier switches on and no input signal is applied. After 1 s the SVR is fully charged and the output dc voltage is set. The MCU sends the PLAY command and the offset, on all the channels, is checked. In case the detected offset is null or, anyhow, lower than 2 V, the power amplifier is kept alive and the audio signal can be applied after 100 ms.

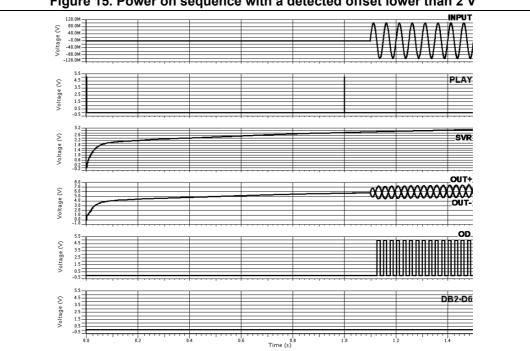


Figure 15. Power on sequence with a detected offset lower than 2 V



TDA75612LV

Look at the *Figure 16*. The power amplifier switches on and no input signal is applied. After 1 s the SVR is fully charged and the output dc voltage is set. The MCU sends the PLAY command and the offset, on all the channels, is checked. If an offset bigger than 2 V is detected, the power amplifier is switched off within 40 ms.

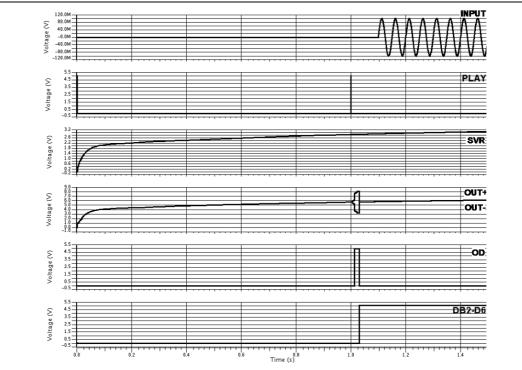


Figure 16. Power on sequence with a detected offset higher than 2 V

This action is pointed out on the I^2C bus, bit DB2-D6. This flag is seen by the microcontroller which can take proper actions.

A standby command (hardware or by I²C) can reset the power amplifier

5.2 Offset detection in normal operation

It is a diagnostics function which has to be performed with low-level output AC signal (or Vin = 0).

The test is run with selectable time duration by microprocessor (from a "start" to a "stop" command):

- Start = Last reading operation or setting IB1 D5 (OFFSET enable) to 1
- Stop = Actual reading operation

Excess offset is signalled out if persistent throughout the assigned testing time. This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.



6 Multiple faults

When more misconnections are simultaneously in place at the audio outputs, it is guaranteed that at least one of them is initially read out. The others are notified after successive cycles of I^2C reading and faults removal, provided that the diagnostic is enabled. This is true for both kinds of diagnostic (Turn-on and Permanent).

The table below shows all the couples of double-fault possible. It should be taken into account that a short circuit with the 4 Ω speaker unconnected is considered as double fault.

	S. GND	S. Vs	S. Across L.	Open L.	
S. GND	S. GND	S. Vs + S. GND	S. GND	S. GND	
S. Vs	/	S. Vs	S. Vs	S. Vs	
S. Across L.	/	/	S. Across L.	N.A.	
Open L.	/	/	/	Open L. (*)	

Table C	Daubla	4		f t		diagonantia
Table 6.	Double	iauit	lable	for turn	on	diagnostic

In Permanent Diagnostic the table is the same, with only a difference concerning Open Load (*), which is not among the recognizable faults. Should an Open Load be present during the device's normal working, it would be detected at a subsequent Turn-on Diagnostic cycle (i.e. at the successive Car Radio Turn-on).

6.1 Faults availability

All the results coming from I²C bus, by read operations, are the consequence of measurements inside a defined period of time. If the fault is stable throughout the whole period, it will be sent out.

To guarantee always resident functions, every kind of diagnostic cycle (Turn-on, Permanent, Offset) is activated again after any l^2C reading operation. So, when the micro reads the l^2C , a new cycle will be able to start, but the read data will come from the previous diag. cycle (i.e. The device is in Turn-on state, with a short to Gnd, then the short is removed and micro reads l^2C . The short to GND is still present in bytes, because it is the result of the previous cycle. If another l^2C reading operation occurs, the bytes do not show the short). In general to observe a change in Diagnostic bytes, two l^2C reading operations are necessary.



7 Thermal protection

Thermal protection is implemented through thermal foldback (Figure 17).

Thermal foldback begins limiting the audio input to the amplifier stage as the junction temperatures rise above the normal operating range. This effectively limits the output power capability of the device thus reducing the temperature to acceptable levels without totally interrupting the operation of the device.

The output power will decrease to the point at which thermal equilibrium is reached. Thermal equilibrium will be reached when the reduction in output power reduces the dissipated power such that the die temperature falls below the thermal foldback threshold. Should the device cool, the audio level will increase until a new thermal equilibrium is reached or the amplifier reaches full power. Thermal foldback will reduce the audio output level in a linear manner.

Three thermal warning are available through the I^2C bus data. After thermal shut down threshold is reached, the CD could toggle (as shown in *Figure 17*) or stay low, depending on signal level.

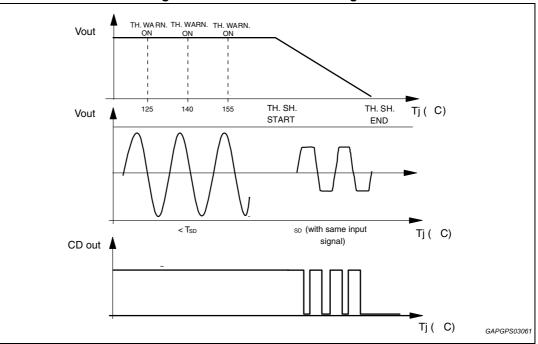


Figure 17. Thermal foldback diagram

7.1 Fast muting

The muting time can be shortened to less than 1.5 ms by setting (IB2) D5 = 1. This option can be useful in transient battery situations (i.e. during car engine cranking) to quickly turnoff the amplifier for avoiding any audible effects caused by noise/transients being injected by preamp stages. The bit must be set back to "0" shortly after the mute transition.

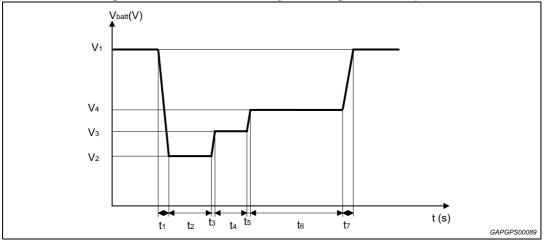


8 Battery transitions management

8.1 Low voltage operation ("start stop")

The most recent OEM specifications are requiring automatic stop of car engine at traffic light, in order to reduce emissions of polluting substances. The TDA75612LV, thanks to its innovating design, allows to go on playng sound when battery falls down to 6/7 V during such conditions, without producing pop noise. The maximum system power will be reduced accordingly.

Supported battery cranking curves are shown below, indicating the shape and durations of allowed battery transitions.





V1 = 12 V; V2 = 6 V; V3 = 7 V; V4 = 8 V

t1 = 2 ms; t2 = 50 ms; t3 = 5 ms; t4 = 300 ms; t5 =10 ms; t6 = 1 s; t7 = 2 ms

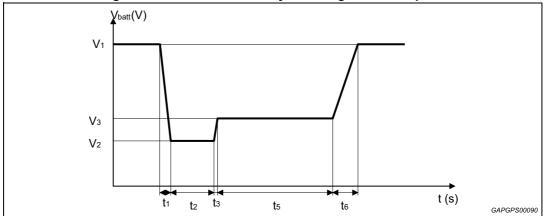


Figure 19. Worst case battery cranking curve sample 2

V1 = 12 V; V2 = 6 V; V3 = 7 V

t1 = 2 ms; t2 = 5 ms; t3 = 15 ms; t5 = 1 s; t6 = 50 ms



8.2 Advanced battery management

In addition to compatibility with low V_{batt} , the TDA75612LV is able to sustain upwards fast battery transitions (like the one showed in *Figure 20*) without causing unwanted audible effect, thanks to the innovative circuit topology.

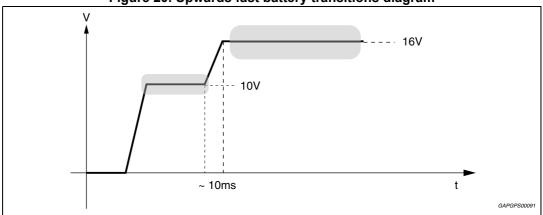


Figure 20. Upwards fast battery transitions diagram

9 I^2C bus

9.1 I²C programming/reading sequences

A correct turn on/off sequence with respect to the diagnostic timings and producing no audible noises could be as follows (after battery connection):

- Turn-on: PIN2 > 4.5 V wait for 10 ms (STAND-BY OUT + DIAG ENABLE) wait for 1s - Muting out (play with no signal) - wait for 100ms
- Turn-off: MUTING IN wait for 50 ms HW ST-BY IN (ST-BY pin ≤ 1.2 V)
- Car Radio Installation: PIN2 > 4.5 V wait for 10 ms DIAG ENABLE (write) wait for 200 ms - I²C read (repeat until all faults disappear).

9.2 Address selection and I²C disable

When the ADSEL/I2CDIS pin is left open the I^2C bus is disabled and the device can be controlled by the STBY/MUTE pin.

In this status (no - I^2C bus) the DATA pin sets the gain (0 = 30 dB; 1 = 16 dB).

When the ADSEL/I2CDIS pin is connected to GND the I^2C bus is active with address <1101100-x>.

To select the other I²C address a resistor must be connected to ADSEL/I2CDIS pin as following:

- 0 < R < 1 kΩ: I²C bus active with address <1101100x>
- 11 kΩ < R < 21 kΩ: I²C bus active with address <1101101x>
- 40 k Ω < R < 70 k Ω : I²C bus active with address <1101110x>
- $R > 120 \text{ k}\Omega$: Legacy mode

(x: read/write bit sector)

9.3 I²C bus interface

Data transmission from microprocessor to the TDA75612LV and viceversa takes place through the 2 wires I^2C bus interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

9.3.1 Data validity

As shown by *Figure 21*, the data on the SDA line must be stable during the high period of the clock. The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

9.3.2 Start and stop conditions

As shown by *Figure 22* a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH. The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.



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9.3.3 Byte format

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

9.3.4 Acknowledge

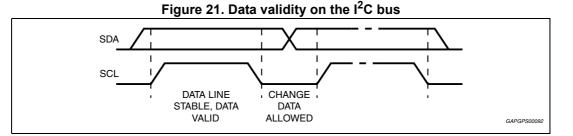
The transmitter* puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see *Figure 23*). The receiver** has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during this clock pulse.

* Transmitter:

- master (µP) when it writes an address to the TDA75612LV
- slave (TDA75612LV) when the μP reads a data byte from TDA75612LV

** Receiver:

- slave (TDA75612LV) when the μ P writes an address to the TDA75612LV
- master (µP) when it reads a data byte from TDA75612LV



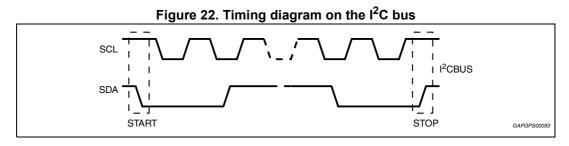
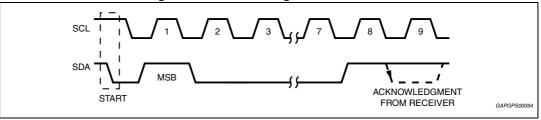


Figure 23. Acknowledge on the I²C bus





10 Software specifications

All the functions of the TDA75612LV are activated by $\mathsf{I}^2\mathsf{C}$ interface.

The bit 0 of the "ADDRESS BYTE" defines if the next bytes are write instruction (from μ P to TDA75612LV) or read instruction (from TDA75612LV to μ P).

Chip address

D7							D0	
1	1	0	1	1	(*)	(*)	Х	D8 Hex

X = 0 Write to device

X = 1 Read from device

If R/W = 0, the μ P sends 2 "Instruction Bytes": IB1 and IB2.

(*) Address selector bit, please refer to address selection description on Chapter 9.2.

Tab	ما	7	IR1
Iau	ıe.	1.	ID I

Bit	Instruction decoding bit
D7	Supply transition mute threshold high (D7 = 1) Supply transition mute threshold low (D7 = 0)
D6	Diagnostic enable (D6 = 1) Diagnostic defeat (D6 = 0)
D5	Offset Detection enable (D5 = 1) Offset Detection defeat (D5 = 0)
D4	Front Channel (CH1, CH3) Gain = 30 dB (D4 = 0) Gain = 16 dB (D4 = 1)
D3	Rear Channel (CH2, CH4) Gain = 30 dB (D3 = 0) Gain = 16 dB (D3 = 1)
D2	Mute front channels (D2 = 0) Unmute front channels (D2 = 1)
D1	Mute rear channels (D1 = 0) Unmute rear channels (D1 = 1)
D0	CD 2% (D0 = 0) CD 10% (D0 = 1)



Bit	Instruction decoding bit				
D7	Current detection threshold High th (D7 = 0) Low th (D7 =1)				
D6	0				
D5	Normal muting time (D5 = 0) Fast muting time (D5 = 1)				
D4	Stand-by on - Amplifier not working - (D4 = 0) Stand-by off - Amplifier working - (D4 = 1)				
D3	Power amplifier mode diagnostic (D3 = 0) Line driver mode diagnostic (D3 = 1)				
D2	Current Detection Diagnostic Enabled (D2 =1) Current Detection Diagnostic Defeat (D2 =0)				
D1	0				
D0	SSR disabled (D0 = 0) SSR enabled (D0 = 1)				

Table 8. IB2

If R/W = 1, the TDA75612LV sends 4 "Diagnostics Bytes" to μ P: DB1, DB2, DB3 and DB4.

Bit	Instruction decoding bit					
D7	Thermal warning 1 active (D7 = 1), T_j = 160 °C (Typ)	-				
D6	Diag. cycle not activated or not terminated (D6 = 0) Diag. cycle terminated (D6 = 1)	-				
D5	Channel LF (CH1) Current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel LF (CH1) Current detection IB2 (D7) = 1 Output peak current < 125 mA - Open load (D5 = 1) Output peak current > 250 mA - Normal load (D5 = 0)				
D4	Channel LF (CH1) Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)	-				
D3	Channel LF (CH1) Normal load (D3 = 0) Short load (D3 = 1)	-				
D2	Channel LF (CH1) Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Offset diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)	-				

Table 9. DB1



1

Bit	Instruction decoding bit				
D1	Channel LF (CH1) No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)	-			
D0	Channel LF (CH1) No short to GND (D1 = 0) Short to GND (D1 = 1)	-			

Table 9. DB1 (continued)

Table 10. DB2

Bit	Instruction decoding bit					
D7	Offset detection not activated (D7 = 0) Offset detection activated (D7 = 1)	-				
D6	Offset detected and automute (SSR) (D6=1)	-				
D5	Channel LR (CH2) Current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel LR (CH2) Current detection IB2 (D7) = 1 Output peak current < 125 mA - Open load (D5 = 1) Output peak current > 250 mA - Normal load (D5 = 0)				
D4	Channel LR (CH2) Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)	-				
D3	Channel LR (CH2) Normal load (D3 = 0) Short load (D3 = 1)	-				
D2	Channel LR (CH2) Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)	-				
D1	Channel LR (CH2) No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)	-				
D0	Channel LR (CH2) No short to GND (D1 = 0) Short to GND (D1 = 1)	-				



Bit	it Instruction decoding bit					
D7	Standby status (= IB2 - D4)	-				
D6	Diagnostic status (= IB1 - D6)	-				
D5	Channel RF (CH3) Current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel RF (CH3) Current detection IB2 (D7) = 1 Output peak current < 125 mA - Open load (D5 = 1) Output peak current > 250 mA - Normal load (D5 = 0)				
D4	Channel RF (CH3) Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)	-				
D3	Channel RF (CH3) Normal load (D3 = 0) Short load (D3 = 1)	-				
D2	Channel RF (CH3) Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)	-				
D1	Channel RF (CH3) No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)	-				
D0	Channel RF (CH3) No short to GND (D1 = 0) Short to GND (D1 = 1)	-				

Table 11. DB3



Bit	Instruction d	ecoding bit
D7	Thermal warning 2 active (D7 = 1), T_j = 145 °C (Typ)	-
D6	Thermal warning 3 active (D6 = 1) T_j = 125 °C (Typ)	-
D5	Channel RR (CH4) Current detection IB2 (D7) = 0 Output peak current < 250 mA - Open load (D5 = 1) Output peak current > 500 mA - Normal load (D5 = 0)	Channel RR (CH4) Current detection IB2 (D7) = 1 Output peak current < 125 mA - Open load (D5 = 1) Output peak current > 250 mA - Normal load (D5 = 0)
D4	Channel RR (CH4) Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)	-
D3	Channel R (CH4) R Normal load (D3 = 0) Short load (D3 = 1)	-
D2	Channel RR (CH4) Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)	-
D1	Channel RR (CH4) No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)	-
D0	Channel RR (CH4) No short to GND (D1 = 0) Short to GND (D1 = 1)	-

Table 12. DB4



11 Examples of bytes sequence

1 - Turn-on diagnostic - Write operation

2 - Turn-on diagnostic - Read operation

Start	Address byte with D0 = 1	ACK	DB1	ACK	DB2	ACK	DB3	ACK	DB4	ACK	STOP	
-------	--------------------------	-----	-----	-----	-----	-----	-----	-----	-----	-----	------	--

The delay from 1 to 2 can be selected by software, starting from 1 ms

3a - Turn-on of the power amplifier with 30 dB gain, mute on, diagnostic defeat, CD = 2 %

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
· · · · · · · · · · · · · · · · · · ·		X0000000		XXX1XX11			

3b - Turn-off of the power amplifier

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
		X0XXXXXX		XXX0XXXX			

4 - Offset detection procedure enable

	Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
		XX1XX11X		XXX1XXXX				

5 - Offset detection procedure stop and reading operation (the results are valid only for the offset detection bits (D2 of the bytes DB1, DB2, DB3, DB4)

Start Address byte with D0 = 1 ACK D	B1 ACK D	DB2 ACK DB3	ACK DB4	ACK S	TOP
--------------------------------------	----------	-------------	---------	-------	-----

 The purpose of this test is to check if a D.C. offset (2 V typ.) is present on the outputs, produced by input capacitor with anomalous leakage current or humidity between pins.

• The delay from 4 to 5 can be selected by software, starting from 1ms



12 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: <u>www.st.com</u>.

 $ECOPACK^{\mathbb{R}}$ is an ST trademark.

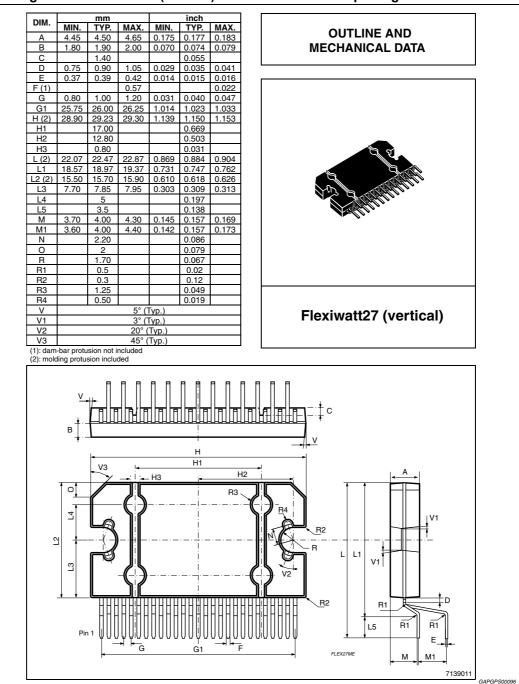


Figure 24. Flexiwatt27 (vertical) mechanical data and package dimensions



13 Revision history

Date	Revision	Changes
05-Dec-2012	1	Initial release.
10-Feb-2014	2	Updated Section 9.1: I ² C programming/reading sequences on page 25.
05-May-2014	3	Updated Figure 17: Thermal foldback diagram on page 22 and Section 9.2: Address selection and l^2C disable on page 25.
22-Sep-2014	4	Updated Section 9.1: I ² C programming/reading sequences on page 25.

Table 13. Document revision history



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